



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re: Application of: SINGH, et al.

Application No.: 10/081,979

Examiner: Marcheschi, Michael A.

Date Filed: February 22, 2002

Group: 1755

For: CHEMICAL-MECHANICAL POLISHING SLURRY FOR  
POLISHING OF COPPER OR SILVER FILMS

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CERTIFICATE UNDER 37 CFR 1.8(a)

I hereby certify that this correspondence is being deposited with the U.S. Postal Service as First Class mail in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA, 22313-1450, on

10/08/03

Neil R. Jetter

Reg. No. 46,803

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

RESPONSE TO NOTICE OF NON-COMPLIANT  
AMENDMENT (37 CFR 1.121)

Sir:

This is responsive to the Notice of Non-Compliant Amendment mailed September 29, 2003 (a copy is attached for your convenience), which requested a complete listing of all of the claims in Applicant's Amendment dated September 11, 2003. Accordingly, below is a listing of all claims including withdrawn claims 38-43:

IN THE CLAIMS:

1. (Currently amended) A slurry for chemical mechanical polishing (CMP) of a copper or silver containing film, comprising:

a solution ~~providing at least one reagent~~ including at least species selected from the group consisting of a polyhalide ion, I<sub>2</sub>, Br<sub>2</sub> and F<sub>2</sub> for reacting with said copper or silver film to form a